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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hiroshi SUZUKI et al.

S.N.: 09/331,829

Filed: June 23, 1999

For: CURATIVES FOR EPOXY RESIN, CURING)
ACCELERATOR, AND EPOXY RESIN
COMPOSITION

Examiner: R. Sellers

Art Unit: 1712

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Luann McCormick, Legal Assistant

RESPONSE AFTER FINAL OFFICE ACTION

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Dear Sir:

In response to the (FINAL) Examiner's Action mailed May 29, 2003 (Paper No. 34), having a shortened statutory period for response set to expire August 29, 2003, the above-identified patent application is amended as follows:

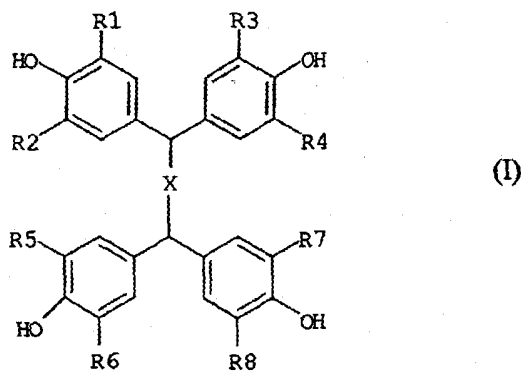
precipitate the crystals. After taking out the crystals by means of filtration, the crystals were dried under reduced pressure to obtain the clathrate according to the present invention. The results during the preparation of the clathrates were presented in Tables 1 and 2. All samples of the clathrates obtained according to the processes described in the examples were determined as the objective clathrates by means of measuring IR spectrums, NMR spectrums, and thermal analysis (TG • DTA and/or DSC) and powder X-ray diffraction pattern analysis. The abbreviations in Tables 1 and 2 represent respectively any of a curative, a curing accelerator or a host compound as described in the following.

Curatives and Curing accelerators:

DEA : Diethylamine
TEA : Triethylamine
PRI : Piperidine
PRA : Piperazine
PY : Pyridine
EDA : Ethylenediamine
TMDA : Trimethylenediamine
TMDA : Tetramethylenediamine
HMDA : Hexamethylenediamine
DETA : Diethylenetriamine
TEBA : Triethylenediamine
o-PDA : Ortho-phenylenediamine
m-PDA : Meta-phenylenediamine
p-PDA : Para-phenylenediamine
BMAEE : Bis(2-dimethylaminoethyl)ether
DMAH : N,N-dimethylaminohexanol
TMHM : N,N,N',N'-tetramethylhexamethylenediamine
2E4MZ : 2-Ethyl-4-methylimidazole
1B2MZ : 1-Benzyl-2-methylimidazole
1I2MZ : 1-Isopropyl-2-methylimidazole
2MZ : 2-Methylimidazole
2PZ : 2-Phenylimidazole
2PZL : 2-Phenylimidazoline
DBU : 1,8-Diazabicyclo(5,4,0)undecene

wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

29. (Currently Amended) An epoxy resin composition, comprising ~~a non-~~
curing an epoxy resin prior to curing, and a clathrate comprising a tetrakisphenol compound
 represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy
 resin to cure the resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

30. (Previously added and withdrawn due to restriction requirement) An epoxy
 resin composition comprising a non-curing epoxy resin, and